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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
JUI-WEN HUNG	10/12/2007
CHING-BAI HWANG	10/12/2007
JIE ZHANG	10/12/2007

RECEIVING PARTY DATA

Name:	Fu Zhun Precision Industry (Shen Zhen) Co., Ltd.	
Street Address:	No. 2, 2nd Donghuan Road,Longhua Town, Bao' an District	
City:	Shenzhen City, Guangdong Province	
State/Country:	CHINA	

Name:	Foxconn Technology Co., Ltd.	
Street Address:	3-2,CHUNG SHAN ROAD	
City:	Tu-Cheng,Taipei Hsien	
State/Country:	TAIWAN	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	11873786

CORRESPONDENCE DATA

500377754

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Correspondent Name: Jeffrey Knapp

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ATTORNEY DOCKET NUMBER: US15720

PATENT

REEL: 019975 FRAME: 0885

NAME OF SUBMITTER:

Jeffrey Todd Knapp

Total Attachments: 2
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PATENT REEL: 019975 FRAME: 0886

ASSIGNMENT

In consideration of value received, the receipt and sufficiency of which are hereby acknowledged, the undersigned ASSIGNOR(S)

1.	Jui-Wen Hung	, residing at	Tu-Cheng, Taipei, Taiwan
2.	Ching-Bai Hwang	, residing at	Tu-Cheng, Taipei, Taiwan
3.	Jie Zhang	, residing at	Shenzhen, Guangdong, China
4.		, residing at	
5.		, residing at	
6.		, residing at	
7.		, residing at	
8.		, residing at	
			

hereby sell(s), assign(s) and transfer(s) unto: Fu Zhun Precision Industry (Shen Zhen) Co., Ltd. having a principal place of business at No.2, 2nd Donghuan Road, Longhua Town, Bao'an District, Shenzhen City, Guangdong Province 518109, P.R.C. and Foxconn Technology Co., Ltd. having a principal place of business at 3-2, Chung Shan Road, Tu-Cheng City, Taipei Hsien, Taiwan, R.O.C. hereafter designated "ASSIGNEE" the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100, in the invention and all patent applications including any and all divisions, continuations, substitutes, and reissues thereof, and all resulting patents, known as RESILIENT CLIP AND THERMAL MODULE USING THE SAME for which the undersigned

[] previously executed Ser. No.	and filing date of	
[x]	is executing concurrently herewith		
an ap	oplication for Letters Patent of United States of	f America	

AND the undersigned hereby authorize(s) and request(s) the United States Commissioner of Patents and Trademarks to issue said Letters Patent to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agree(s) that the attorneys of record in said application, if any, shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agree(s) to testify and execute any papers for ASSIGNEE, its successors, assigns and legal representatives, deemed essential by ASSIGNEE to ASSIGNEE's full protection and title in and to the invention hereby transferred.

1

PATENT REEL: 019975 FRAME: 0887

1.	frie-wen 14	ung	Oct.12,2007	
1.	Jui-Wen Hung	nventor	Date	Witness
2.	Ching-Bai Hwang Ching-Bai Hwang		Oct.12,2007	
	Ching-Bai Hwang	inventor	Date	Witness
3.	J.e zhang		Oct.12,2007	
	Jic Zhang	inventor	Date	Witness
4.				
		inventor	Date	Witness
5.				
٦.		inventor	Date	Witness
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6.		inventor	Date	Witness
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7.		inventor	Date	Witness
8.		inventor	Date	Witness